



TCA9617B Level-Translating FM+ I²C Bus Repeater

1 Features

- Two-Channel Bidirectional I²C Buffer
- Support for Standard Mode, Fast Mode (400 kHz), and Fast Mode+ (1 MHz) I²C Operation
- Operating Supply Voltage Range of 0.8 V to 5.5 V on A-Side
- Operating Supply Voltage Range of 2.2 V to 5.5 V on B-Side
- Voltage-Level Translation From 0.8 V to 5.5 V and 2.2 V to 5.5 V
- Footprint and Function Replacement for TCA9517
- Active-High Repeater-Enable Input
- Open-Drain I²C I/O
- 5.5-V Tolerant I²C and Enable Input Support
- Lockup-Free Operation
- Powered-Off High-Impedance I²C Bus Pins
- Support for Clock Stretching and Multiple Master Arbitration Across The Device
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 4000-V Human-Body Model (A114-A)
 - 1500-V Charged-Device Model (C101)

2 Applications

- Servers
- Routers (Telecom Switching Equipment)
- Industrial Equipment
- Products With Many I²C Slaves and/or Long PCB Traces

3 Description

The TCA9617B is a BiCMOS dual bidirectional buffer intended for I²C bus and SMBus systems. It can provide bidirectional voltage-level translation (up-translation and down-translation) between low voltages (down to 0.8 V) and higher voltages (2.2 V to 5.5 V) in mixed-mode applications. This device enables I²C and similar bus systems to be extended, without degradation of performance even during level shifting.

The TCA9617B buffers both the serial data (SDA) and the serial clock (SCL) signals on the I²C bus, allowing two buses of 550 pF to be connected in an I²C application. This device can also be used to isolate two halves of a bus for voltage and capacitance.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TCA9617B	VSSOP (8)	3.00 mm x 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

4 Simplified Schematic

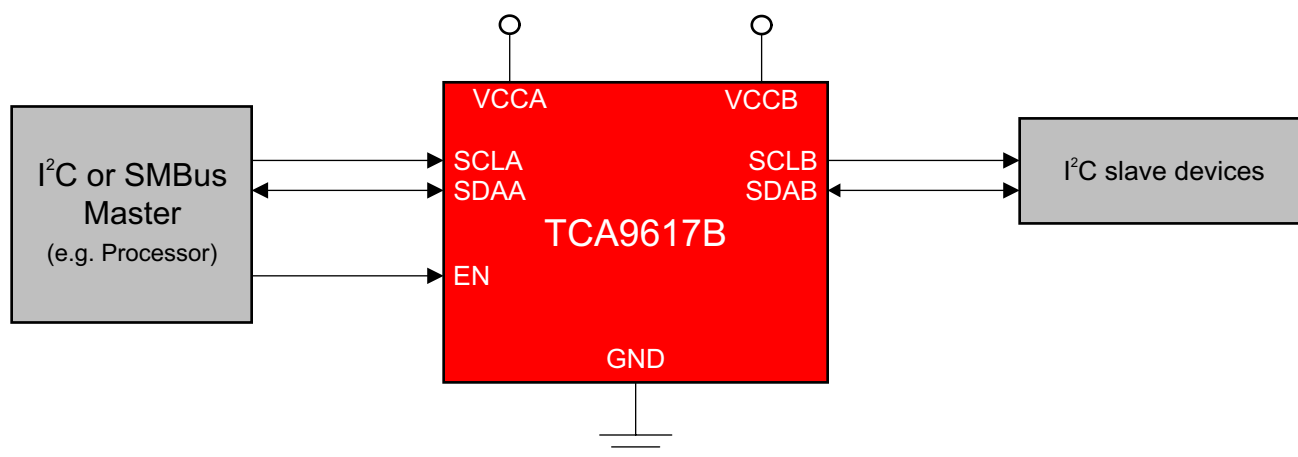


Table of Contents

1 Features	1	9.1 Overview	9
2 Applications	1	9.2 Functional Block Diagram	10
3 Description	1	9.3 Feature Description	10
4 Simplified Schematic	1	9.4 Device Functional Modes	11
5 Revision History	2	10 Application and Implementation	12
6 Pin Configuration and Functions	3	10.1 Application Information	12
7 Specifications	3	10.2 Typical Application	12
7.1 Absolute Maximum Ratings	3	11 Power Supply Recommendations	15
7.2 ESD Ratings	3	12 Layout	16
7.3 Recommended Operating Conditions	4	12.1 Layout Guidelines	16
7.4 Thermal Information	4	12.2 Layout Example	16
7.5 Electrical Characteristics	5	13 Device and Documentation Support	17
7.6 Timing Requirements	6	13.1 Trademarks	17
7.7 Typical Characteristics	6	13.2 Electrostatic Discharge Caution	17
8 Parameter Measurement Information	7	13.3 Glossary	17
9 Detailed Description	9	14 Mechanical, Packaging, and Orderable Information	17

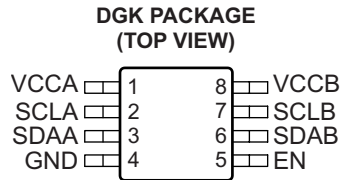
5 Revision History

Changes from Original (December 2014) to Revision A

Page

• Initial release of full version.	1
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6 Pin Configuration and Functions



Pin Functions

PIN		DESCRIPTION
NAME	NO.	
EN	5	Active-high repeater enable input
GND	4	Supply ground
SCLA	2	I ² C SCL line, A side. Connect to V _{CCA} through a pull-up resistor.
SCLB	7	I ² C SCL line, B side. Connect to V _{CCB} through a pull-up resistor.
SDAA	3	I ² C SDA line, A side. Connect to V _{CCA} through a pull-up resistor.
SDAB	6	I ² C SDA line, B side. Connect to V _{CCB} through a pull-up resistor.
VCCA	1	A-side supply voltage (0.8 V to 5.5 V)
VCCB	8	B-side and device supply voltage (2.2 V to 5.5 V)

7 Specifications

7.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CCB}	Supply voltage range		–0.5	7	V
V _{CCA}	Supply voltage range		–0.5	7	V
V _I	Enable input voltage range ⁽²⁾		–0.5	7	V
V _{I/O}	I ² C bus voltage range ⁽²⁾		–0.5	7	V
I _{IK}	Input clamp current	V _I < 0		–50	mA
I _{OK}	Output clamp current	V _O < 0		–50	
I _O	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
T _{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

7.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±4000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1500

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

TCA9617B

SCPS259A –DECEMBER 2014–REVISED DECEMBER 2014

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7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CCA}	Supply voltage, A-side bus	0.8	V _{CCB}	V
V _{CCB}	Supply voltage, B-side bus	2.2	5.5	V
I _{OLA}	Low-level output current		30	mA
I _{OLB}	Low-level output current	0.1	30	mA
T _A	Operating free-air temperature	–40	85	°C

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TCA9617B	UNIT
		DGK	
		8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	171.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	61.2	
R _{θJB}	Junction-to-board thermal resistance	93.6	
ψ _{JT}	Junction-to-top characterization parameter	7.9	
ψ _{JB}	Junction-to-board characterization parameter	91.9	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, .

7.5 Electrical Characteristics

 $V_{CCB} = 2.2\text{ V to }5.5\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CCB}	MIN	TYP	MAX	UNIT
V_{IK}	Input clamp voltage	$I_I = -18\text{ mA}$	2.2 V to 5.5 V			-1.2	V
V_{OL}	Low-level output voltage	SDAB, SCLB $I_{OL} = 100\text{ }\mu\text{A or }30\text{ mA}$, $V_{ILA} = 0\text{ V}$	2.2 V to 5.5 V	0.48	0.53	0.58	V
		SDAA, SCLA $I_{OL} = 30\text{ mA}$			0.1	0.23	
V_{IH}	High-level input voltage	SDAA, SCLA	2.2 V to 5.5 V	$0.7 \times V_{CCA}$		5.5	V
		SDAB, SCLB		$0.7 \times V_{CCB}$		5.5	
		EN		$0.7 \times V_{CCB}$		5.5	
V_{IL}	Low-level input voltage	SDAA, SCLA	2.2 V to 5.5 V			$0.3 \times V_{CCA}$	V
		SDAB, SCLB				0.4	
		EN				$0.3 \times V_{CCB}$	
I_{CCA}	Quiescent supply current for V_{CCA}	Both channels low, SDAA = SCLA = GND and $I_{OLB} = 100\text{ }\mu\text{A}$, or SDAA = SCLA = open and SDAB = SCLB = GND	2.2 V to 5.5 V			13	μA
I_{CCB}	Quiescent supply current	Both Channels high, SDAA = SCLA = V_{CCA} B-side pulled up to V_{CCB} with pull-up resistors	5.5 V		+4.5	+7	mA
		Both channels low, SDAA = SCLA = GND, $I_{OLB} = 100\text{ }\mu\text{A}$			+5.7	+8.1	
I_I	Input leakage current	SDAB, SCLB	$V_I = V_{CCB}$			-1	μA
			$V_I = 0.2\text{ V}$, EN = 0			-10	
			$V_I = V_{CCB} - 0.2\text{ V}$			-1	
			$V_I = 5.5\text{ V}$, $V_{CCA} = 0\text{ V}$	0 V		-10	
		SDAA, SCLA	$V_I = V_{CCA}$			-1	
			$V_I = 0.2\text{ V}$, EN = 0			-10	
			$V_I = V_{CCA} - 0.2\text{ V}$			-1	
			$V_I = 5.5\text{ V}$, $V_{CCA} = 0\text{ V}$	0 V		-10	
		EN	$V_I = V_{CCB}$			-1	
			$V_I = 0.2\text{ V}$			-25	
C_I	Input capacitance	EN	$V_I = 3\text{ V or }0\text{ V}$	3.3 V		7	pF
C_{IO}	Input/output capacitance	SCLA, SDAA	$V_I = 3\text{ V or }0\text{ V}$	3.3 V		9	
			0 V			9	
		SCLB, SDAB	$V_I = 3\text{ V or }0\text{ V}$	3.3 V		14	
			0 V			14	

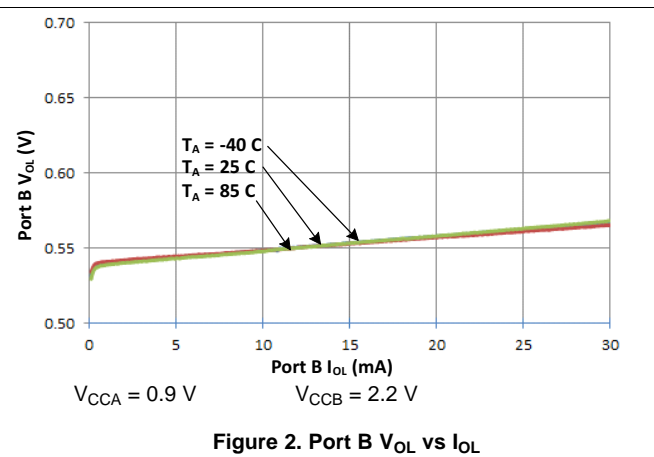
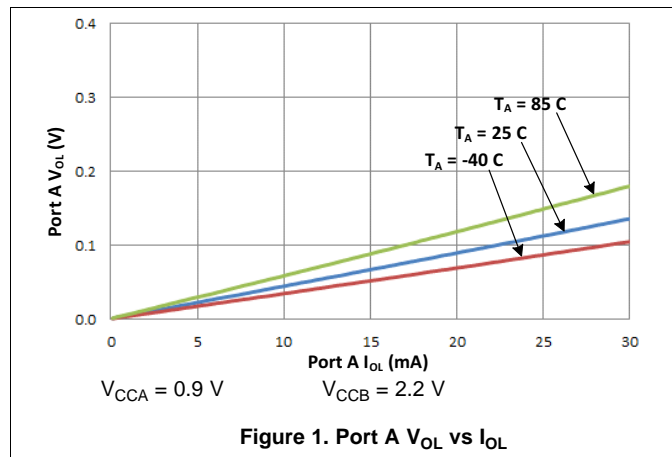
7.6 Timing Requirements

 $V_{CCA} = 0.8 \text{ V to } 5.5 \text{ V}$, $V_{CCB} = 2.2 \text{ V to } 5.5 \text{ V}$, $GND = 0 \text{ V}$, $T_A = -40^\circ\text{C to } 85^\circ\text{C}$ (unless otherwise noted)⁽¹⁾⁽²⁾⁽³⁾

PARAMETER			FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay		SDAB, SCLB	SDAA, SCLA		42	55	90	ns
			SDAA, SCLA	SDAB, SCLB	V _{CCB} ≤ 3 V	61	88	137	
					V _{CCB} > 3 V	61	94	250	
t _{PHL}	Propagation delay		SDAB, SCLB	SDAA, SCLA		69	93	144	ns
			SDAA, SCLA	SDAB, SCLB		68	90	140	
t _{TLH} ⁽⁴⁾	Transition time	B side	30%	70%		88			ns
		A side				37			
t _{THL}	Transition time	B side	70%	30%		5.40	6.41	13.8	ns
		A side				1.40	4.71	11.3	
t _{su,en}	Setup time, EN high before Start condition ⁽⁵⁾					100			ns

- (1) Times are specified with loads of $240 \Omega \pm 1\%$ and $400 \text{ pF} \pm 10\%$ on B-side and $240 \Omega \pm 1\%$ and $200 \text{ pF} \pm 10\%$ on A-side. Different load resistance and capacitance alter the rise time, thereby changing the propagation delay and transition times.
- (2) Times are specified with A-side signals pulled up to V_{CCA} and B-side signals pulled up to V_{CCB} .
- (3) Typical values were measured with $V_{CCA} = 0.9 \text{ V}$ and $V_{CCB} = 2.5 \text{ V}$ at $T_A = 25^\circ\text{C}$, unless otherwise noted.
- (4) T_{TLH} is determined by the pull-up resistance and load capacitance.
- (5) EN should change state only when the global bus and the repeater port are in an idle state.

7.7 Typical Characteristics



8 Parameter Measurement Information

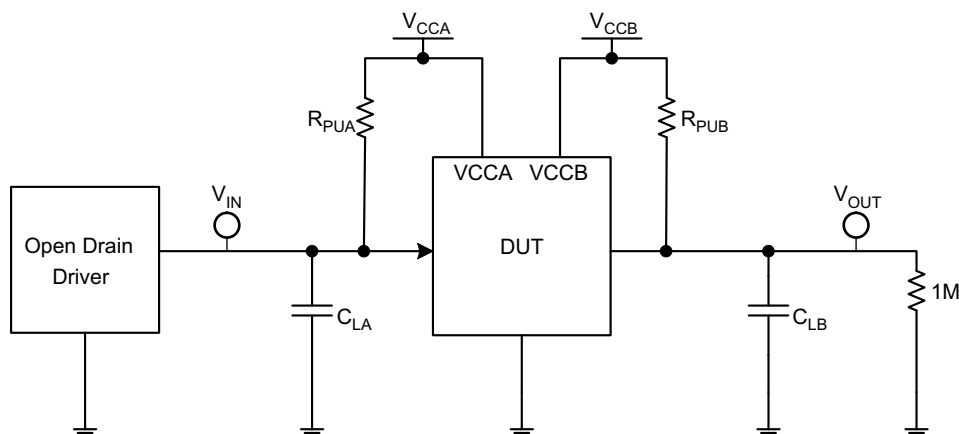
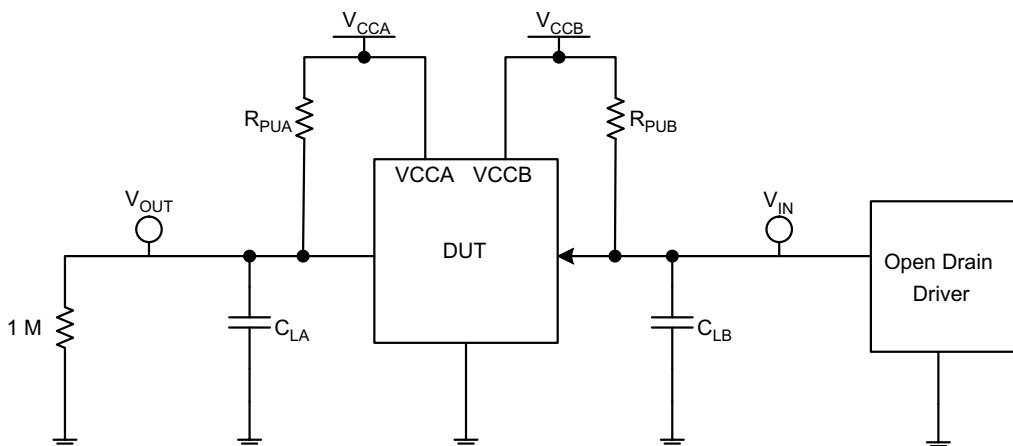
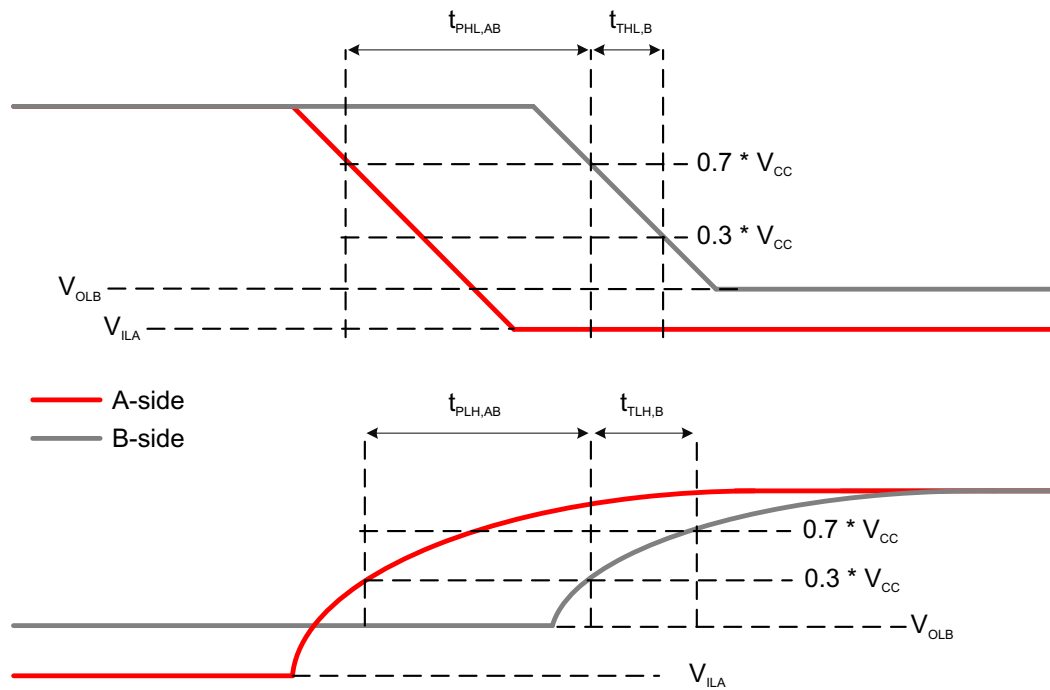
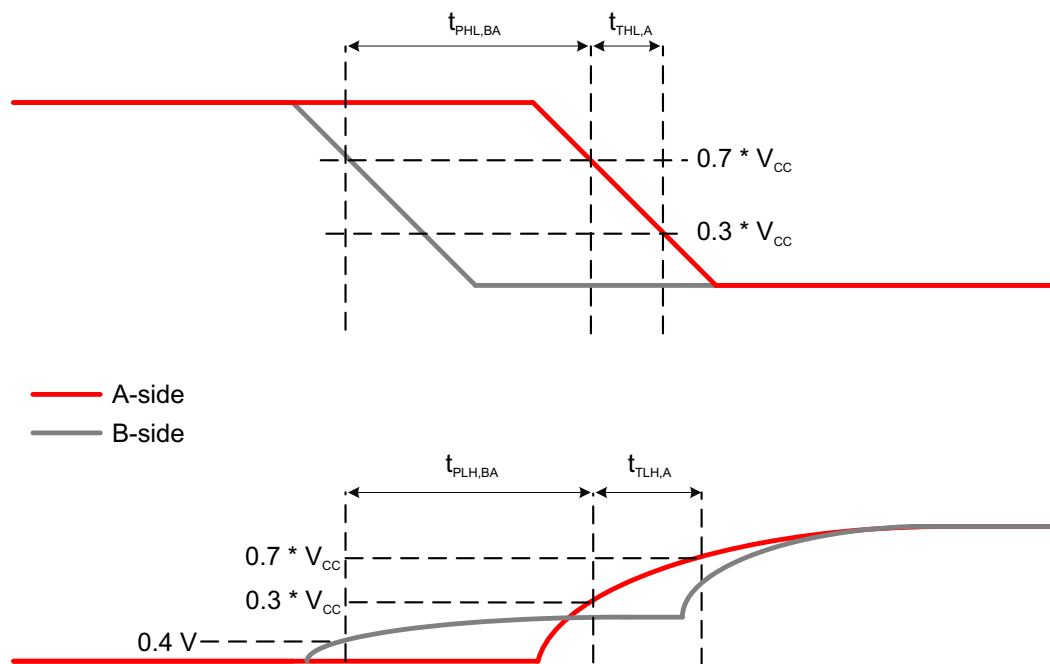


Figure 3. Test Circuit for Open-Drain Output from A to B



- A. $V_{CCA} = 0.9 \text{ V}$
- B. $V_{CCB} = 2.5 \text{ V}$
- C. $R_{PUA} = R_{PUB} = 240 \Omega$ on the A-side and the B-side
- D. $C_{LA} = 200 \text{ pF}$ on A-side and $C_{LB} = 400 \text{ pF}$ on B-side (includes probe and jig capacitance)
- E. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, slew rate $\geq 1 \text{ V/ns}$
- F. The outputs are measured one at a time, with one transition per measurement.

Figure 4. Test Circuit for Open-Drain Output from B to A

Parameter Measurement Information (continued)

Figure 5. Propagation Delay And Transition Times (A to B)

Figure 6. Propagation Delay And Transition Times (B to A)

9 Detailed Description

9.1 Overview

The TCA9617B is a BiCMOS dual bidirectional buffer intended for I²C bus and SMBus systems. As with the standard I²C system, pull-up resistors are required to provide the logic high levels on the buffered bus. The TCA9617B has standard open-drain configuration of the I²C bus. The size of these pull-up resistors depends on the system, but each side of the repeater must have a pull-up resistor. The device is designed to work with Standard mode, Fast mode and Fast Mode+ I²C devices. The SCL and SDA lines shall be at high-impedance when either one of the supplies is powered off.

The TCA9617B B-side drivers operate from 2.2 V to 5.5 V. The output low level for this internal buffer is approximately 0.5 V, but the input voltage must be below V_{IL} when the output is externally driven low. The higher-voltage low signal is called a buffered low. When the B-side I/O is driven low internally, the low is not recognized as a low by the input. This feature prevents a lockup condition from occurring when the input low condition is released. This type of design on the B side prevents it from being used in series with another TCA9617B B-side or other buffers that incorporate a static or dynamic offset voltage. This is because these devices do not recognize buffered low signals as a valid low and do not propagate it as a buffered low again.

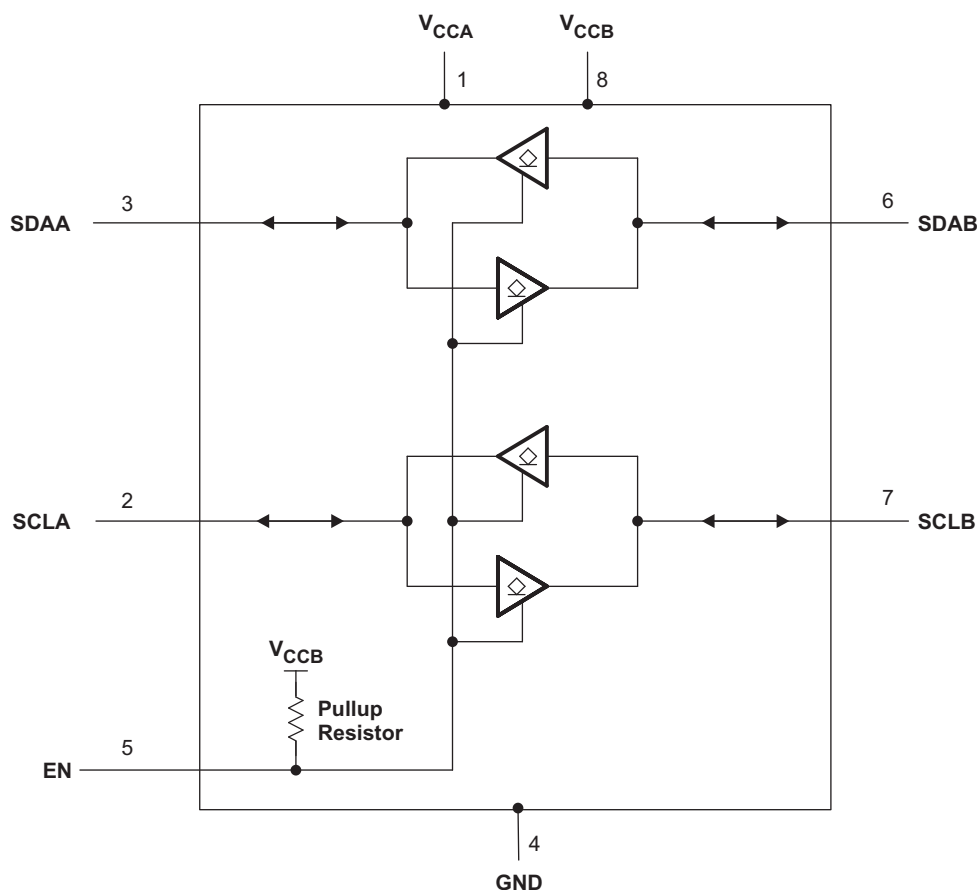
The TCA9617B A-side drivers operate from 0.8 V to 5.5 V and do not have the buffered low feature (or the static offset voltage). This means that a low signal on the B side translates to a nearly 0-V low on the A side, which accommodates smaller voltage swings of low-voltage logic. The output pull-down on the A side drives a hard low, and the input level is set to $0.3 V_{CCA}$ to accommodate the need for a lower low level in systems where the low-voltage-side supply voltage is as low as 0.8 V.

The A side of two or more TCA9617Bs can be connected together to allow a star topology, with the A side on the common bus. Also, the A side can be connected directly to any other buffer with static or dynamic offset voltage. Multiple TCA9617Bs can be connected in series, A side to B side, with no buildup in offset voltage with only time-of-flight delays to consider.

The TCA9617B includes a power-up circuit that keeps the output drivers turned off until V_{CCB} is above 2.0 V and V_{CCA} is above 0.7 V. V_{CCA} is only used to provide references for the A-side input comparators and the power-good-detect circuit. The TCA9617B internal circuitry and all I/Os are powered by the V_{CCB} pin.

After power up and with the EN high, the A side falling below $0.7 V_{CCA}$ turns on the corresponding B-side driver (either SDA or SCL) and drives the B-side down momentarily to 0 V before settling to approximately 0.5 V. When the A-side rises above $0.3 V_{CCA}$, the B-side pull-down driver is turned off and the external pull-up resistor pulls the pin high. If the B side falls first and goes below $0.7 V_{CCB}$, the A-side driver is turned on and drives the A-side to 0 V. When the B-side rises above 0.45 V, the A-side pull-down driver is turned off and the external pull-up resistor pulls the pin high.

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 Bidirectional Level Translation

The TCA9617B can provide bidirectional voltage level translation (up-translation and down-translation) between low voltages (down to 0.8 V) and higher voltages (2.2 V to 5.5 V) in mixed-mode applications.

9.3.2 Low to High Transition Characteristics

Figure 8 depicts the offset voltage on the B side of the device. As shown in Figure 8 the slave releases and the B-side rises, and it will rise to 0.5 V and stay there until the A-side rises above $0.3 V_{CCA}$. This effect can cause the low level signal to have a "pedestal." Once the voltage on the A-side crosses $0.3 V_{CCA}$, the B-side will continue to rise to V_{CCB} .

Due to nature of the B-side pedestal and the static offset voltage, there will be a slight overshoot as the B-side rises from being externally driven low to the 0.5 V offset. The TCA9617B is designed to control this behavior provided the system is designed with rise times greater than 20 ns. Therefore, care should be taken to limit the pull-up strength when devices with rise time accelerators are present on the B side. Excessive overshoot on the B-side pedestal may cause devices with rise time accelerators to trip prematurely if the overshoot is more than accelerator thresholds. Since the A-side does not have a static offset low voltage, no pedestal is seen on the A-side as shown in Figure 7.

Feature Description (continued)

9.3.3 High to Low Transition Characteristics

When the A side of the bus is driven to $0.7 V_{CCA}$, the B side driver will turn on. This will drive the B-side to 0 V for a short period (see Figure 8) and then the B-side will rise to the static offset voltage of 0.5 V (V_{OL} of TCA9617B). This effect, called an inverted pedestal, allows the B-side to drive to logic low much faster than driving to the static offset. Driving to the static offset voltage requires that the fall time be slowed to prevent ringing.

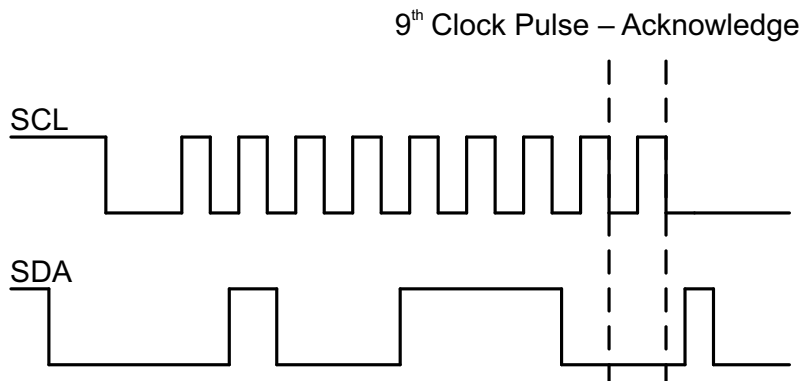


Figure 7. Bus A (0.8 V to 5.5 V Bus) Waveform

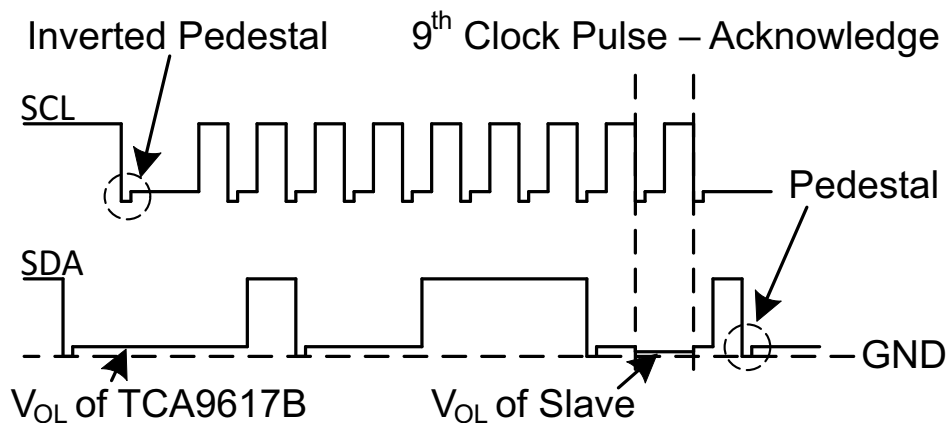


Figure 8. Bus B (2.2 V to 5.5 V Bus) Waveform

9.4 Device Functional Modes

The TCA9617B has an active-high enable (EN) input with an internal pull-up to V_{CCB} , which allows the user to select when the repeater is active. This can be used to isolate a badly behaved slave on power-up reset. It should never change state during an I²C operation, because disabling during a bus operation may hang the bus, and enabling part way through the bus cycles could confuse the I²C parts being enabled. The EN input should change state only when the global bus and repeater port are in the idle state to prevent system failures.

Table 1. Function Table

INPUT EN	FUNCTION
L	Outputs disabled
H	SDAA = SDAB SCLA = SCLB

10 Application and Implementation

10.1 Application Information

A typical application is shown in Figure 9. In this example, the system master is running on a 0.9-V I²C bus, and the slave is connected to a 2.5-V bus. Both buses are running at 400 kHz. Decoupling capacitors are required but are not shown in Figure 14 for simplicity.

The TCA9617B is 5-V tolerant so no additional circuits are required to translate between 0.8-V to 5.5-V bus voltages and 2.7-V to 5.5-V bus voltages.

When the A side of the TCA9617B is pulled low by a driver on the I²C bus, a comparator detects the falling edge when it goes below 0.7 V_{CCA} and cause the internal driver on the B side to turn on. The B-side will first pull down to 0 V and then settle to 0.5 V. When the B side of the TCA9617B falls below 0.45 V, the TCA9617B will detect the falling edge, turn on the internal driver on the A side and pull the A-side pin down to ground.

On the B-side bus of the TCA9617B, the clock and data lines will have a positive offset from ground equal to the V_{OL} of the TCA9617B. After the eighth clock pulse, the data line is pulled to the V_{OL} of the slave device, which is close to ground in this example. At the end of the acknowledge, the level rises only to the low level set by the driver of the TCA9617B for a short delay (approximately 0.5 V), while the A-side bus rises above 0.3 V_{CCA} and then continues high.

Although the TCA9617 has a single application, the device can exist in multiple configurations. Figure 9 shows the standard configuration for the TCA9617. Multiple TCA9617s can be connected either in star configuration (Figure 12) or in series configuration (Figure 13). The design requirements, detailed design procedure, and application curves in [Standard Application](#) are valid for all three configurations.

10.2 Typical Application

10.2.1 Standard Application

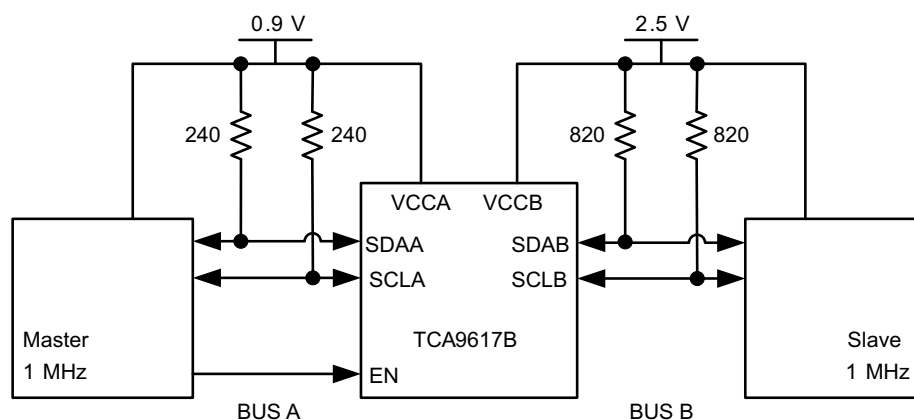


Figure 9. Bidirectional Voltage Level Translator

10.2.1.1 Design Requirements

For the level-translating application, the following should be true:

- V_{CCA} = 0.8 V to 5.5 V
- V_{CCB} = 2.2 V to 5.5 V
- V_{CCA} < V_{CCB}
- I_{OL} > I_O

Typical Application (continued)

10.2.1.2 Detailed Design Procedure

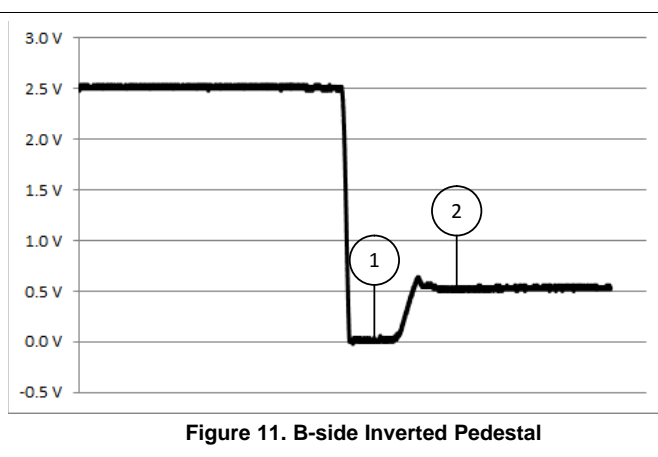
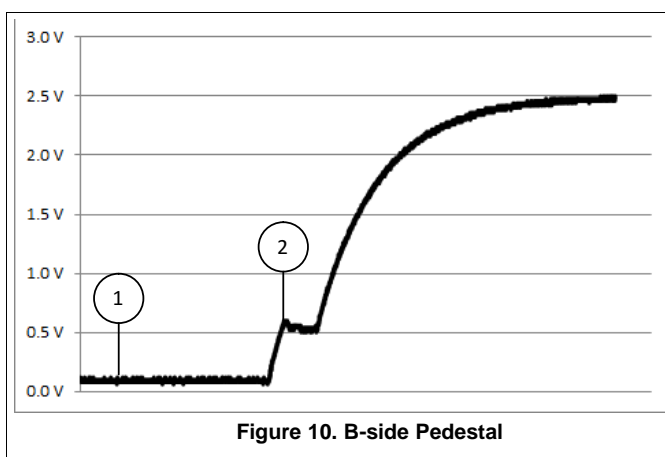
10.2.1.2.1 Pullup Resistor Sizing

For the TCA9617B to function correctly, all devices on the B-side must be able to pull the B-side below the voltage input low contention level (0.45 V). This means that the V_{OL} of any device on the B-side must be below 0.4 V to ensure proper operation.

The V_{OL} of a device can be adjusted by changing the I_{OL} through the device which is set by the pull-up resistor value. The pull-up resistor on the B-side must be carefully selected to ensure that logic levels will be transferred correctly to the A-side.

The B-side pull-up resistor sizing must also ensure that the rise time is greater than 20 ns. Shorter rise times will increase the pedestal overshoot shown in point 2 of [Figure 10](#).

10.2.1.3 Application Curves



Typical Application (continued)

10.2.2 Star Application

Multiple TCA9617B A sides can be connected in a star configuration, allowing all nodes to communicate with each other.

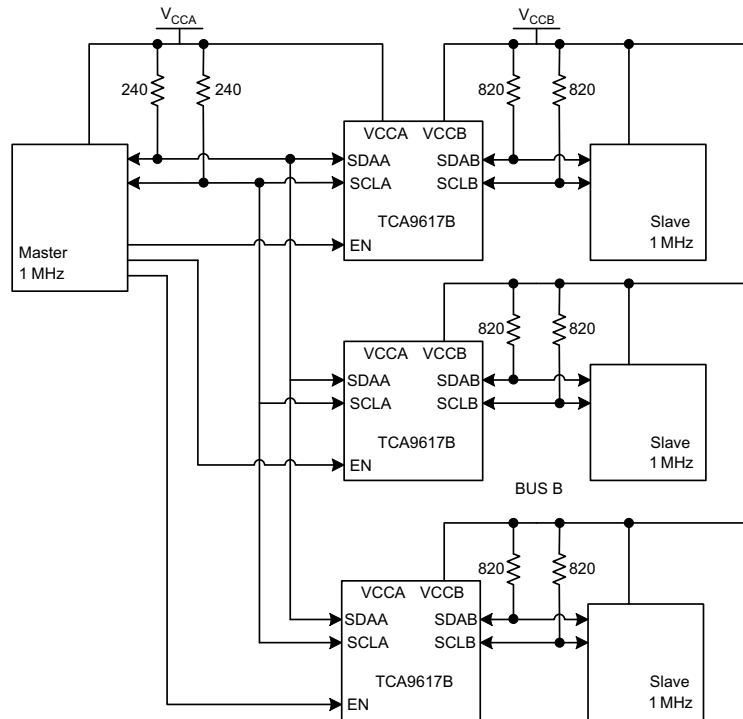


Figure 12. Typical Star Application

10.2.2.1 Design Requirements

Refer to [Design Requirements](#).

10.2.2.2 Detailed Design Procedure

Refer to [Detailed Design Procedure](#).

10.2.2.3 Application Curves

Refer to [Application Curves](#).

Typical Application (continued)

10.2.3 Series Application

Multiple TCA9617Bs can be connected in series as long as the A side is connected to the B side. I²C bus slave devices can be connected to any of the bus segments. The number of devices that can be connected in series is limited by repeater delay/time-of-flight considerations on the maximum bus speed requirements.

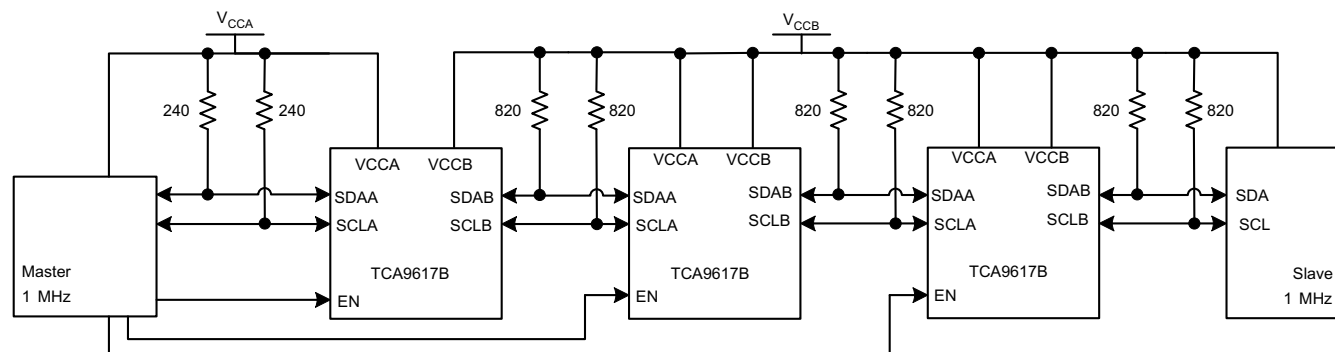


Figure 13. Typical Series Application

10.2.3.1 Design Requirements

Refer to [Design Requirements](#).

10.2.3.2 Detailed Design Procedure

Refer to [Detailed Design Procedure](#).

10.2.3.3 Application Curves

Refer to [Application Curves](#).

11 Power Supply Recommendations

For VCCA, an 0.8-V to 5.5-V power supply is required. For VCCB, a 2.2-V to 5.5-V power supply is required.

Standard decoupling capacitors are recommended. These capacitors typically range from 0.1 μ F to 1 μ F, but the ideal capacitance depends on the amount of noise from the power supply.

12 Layout

12.1 Layout Guidelines

The recommended decoupling capacitors should be placed as close to the VCCA and VCCB pins of the TCA9617B as possible.

12.2 Layout Example

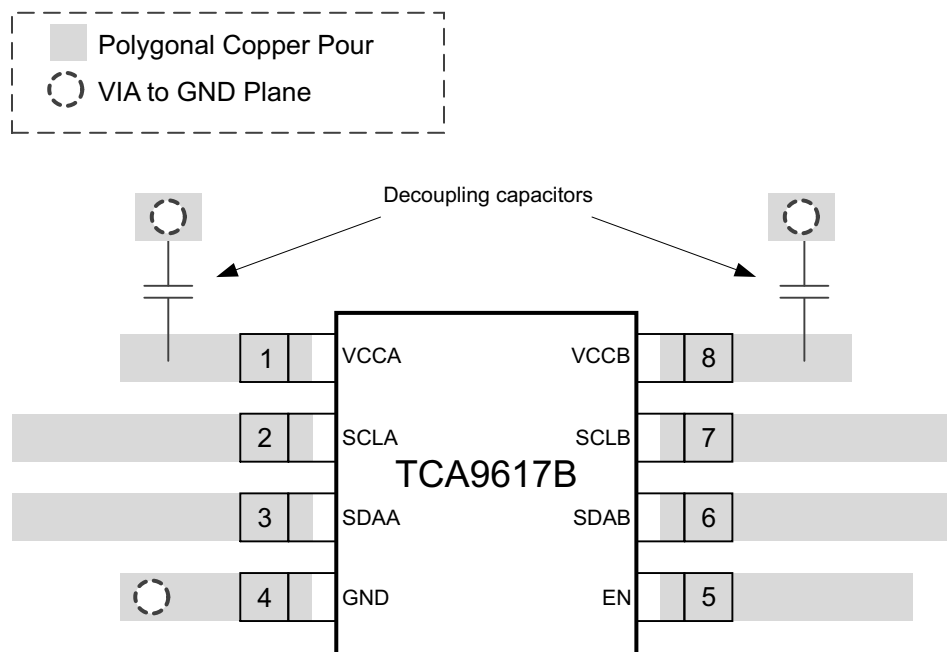


Figure 14. Layout Schematic

13 Device and Documentation Support

13.1 Trademarks

All trademarks are the property of their respective owners.

13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TCA9617BDGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	ZBOK	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

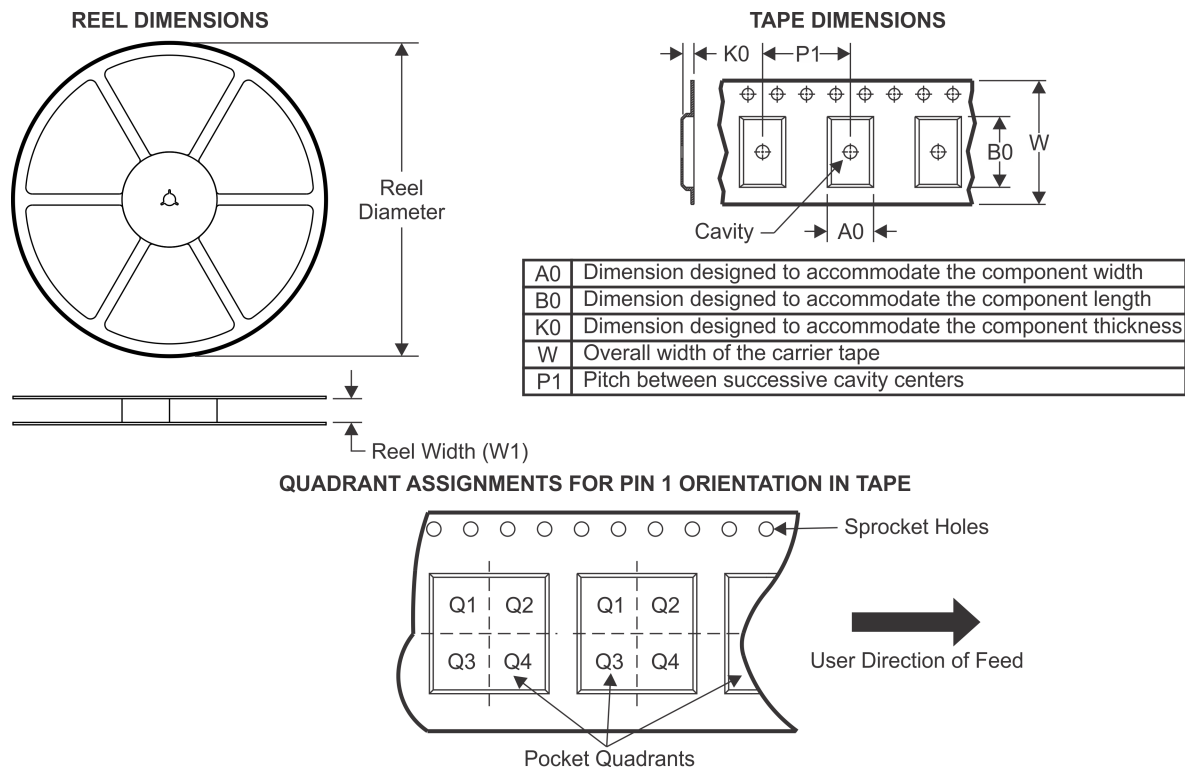
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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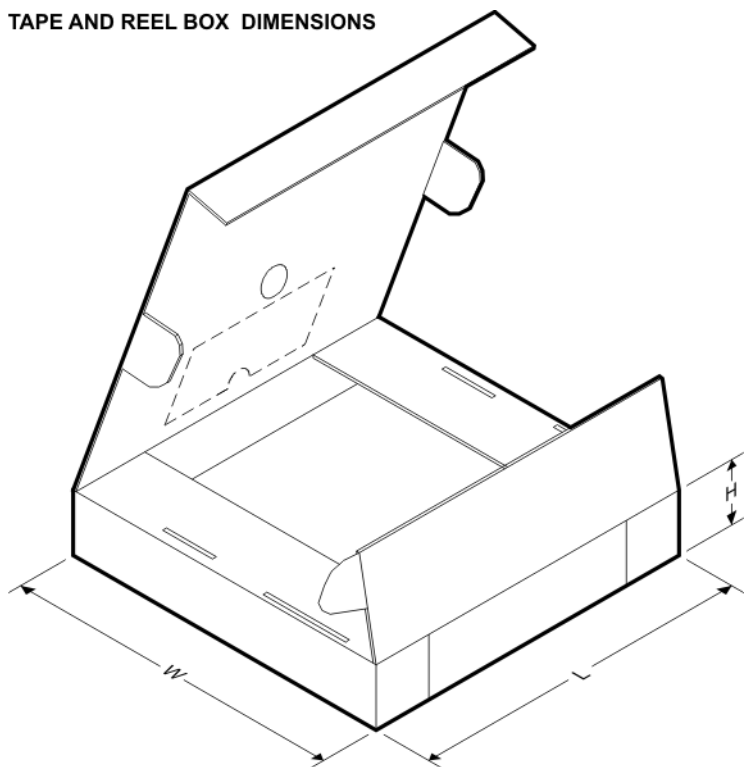
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9617BDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

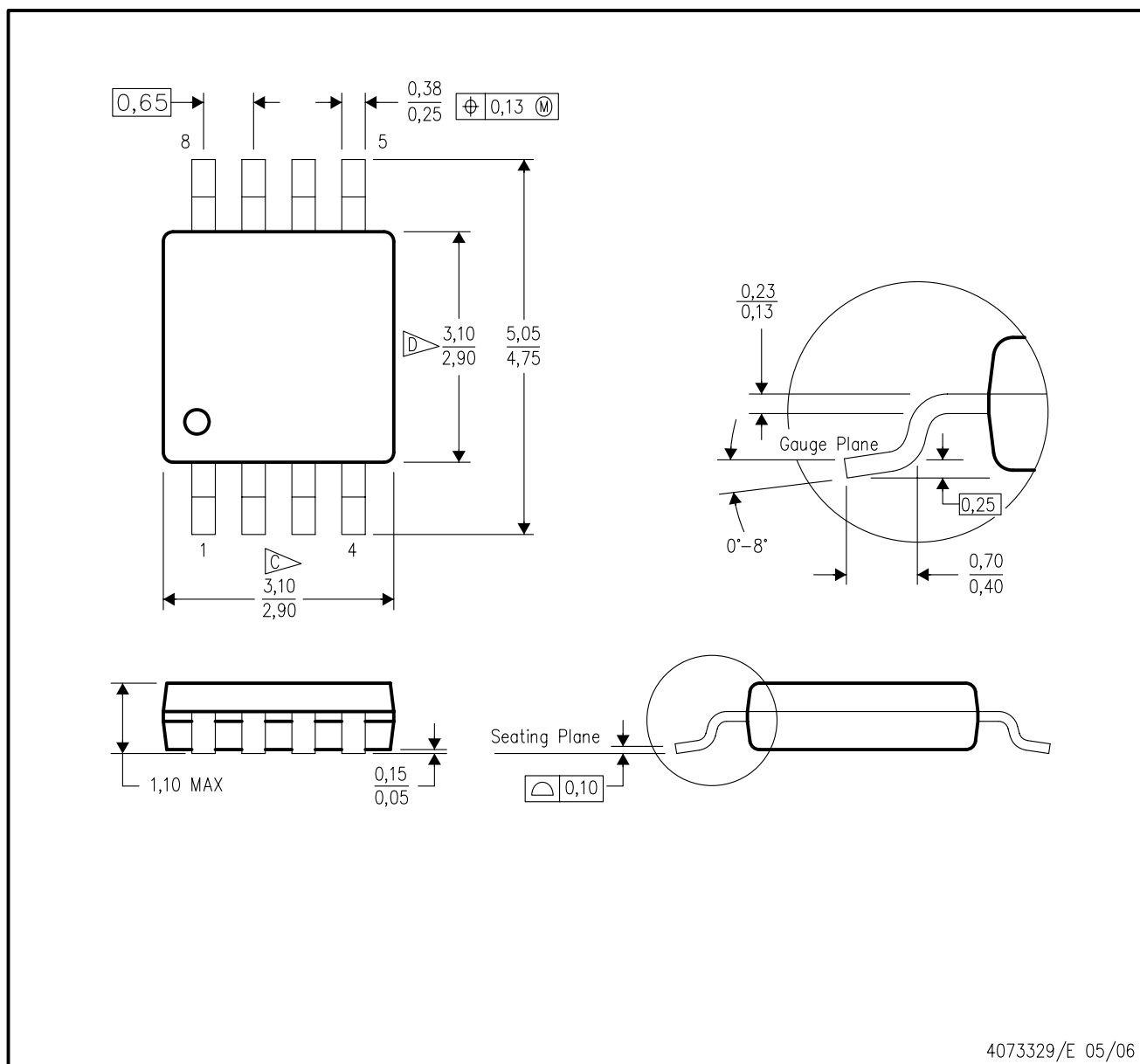


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9617BDGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

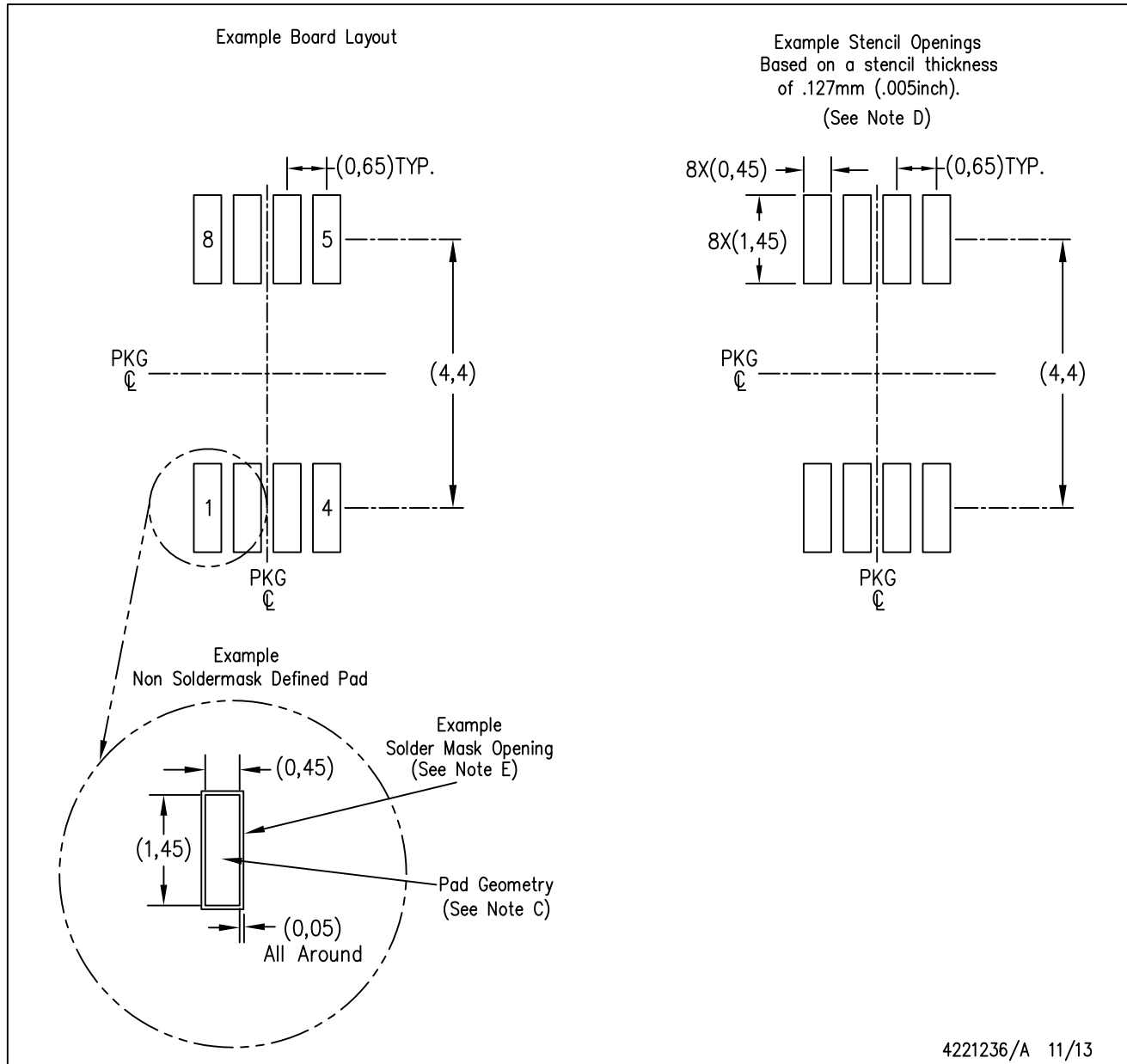


4073329/E 05/06

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

DGK (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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